US00D846511S

(12) United States Design Patent
Nishio et al.

(10) **Patent No.: US D846,511 S**
(45) **Date of Patent: ** Apr. 23, 2019**

(54) **OPTICAL SEMICONDUCTOR ELEMENT**

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(**) Term: **15 Years**

(21) Appl. No.: **29/645,559**

(22) Filed: **Apr. 27, 2018**

Related U.S. Application Data

(62) Division of application No. 35/502,668, filed on Sep. 21, 2016 (U.S. filing date under 35 U.S.C. 384), and

(Continued)

(30) Foreign Application Priority Data

Mar. 24, 2016	(JP)	2016-006372
Mar. 24, 2016	(JP)	2016-006373

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180, 134; D14/371; D9/737; D26/122, 120, 141, 118, 1; 257/98, 88, 257/100, 87; 524/307; 372/45.01

(Continued)

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(57) CLAIM

The ornamental design for an optical semiconductor element, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of an optical semiconductor element of the present invention.

FIG. **2** is a bottom perspective view of the optical semiconductor element of FIG. **1**.

FIG. **3** is a front view of the optical semiconductor element of FIG. **1**.

FIG. **4** is a back view of the optical semiconductor element of FIG. **1**.

FIG. **5** is a top view of the optical semiconductor element of FIG. **1**.

FIG. **6** is a bottom view of the optical semiconductor element of FIG. **1**.

FIG. **7** is a left view of the optical semiconductor element of FIG. **1**.

FIG. **8** is a right view of the optical semiconductor element of FIG. **1**.

FIG. **9** is a sectional view taken along the line **9**-**9** of the optical semiconductor element of FIG. **5**; and,

FIG. **10** is a reference perspective view of the optical semiconductor element of FIG. **1** in use, wherein the optical semiconductor element is attached to a mount board, which is for illustrative purpose only and form no part of the claimed design.

The dash-dot-dash broken lines are for the purpose of illustrating the boundaries of the claimed design.

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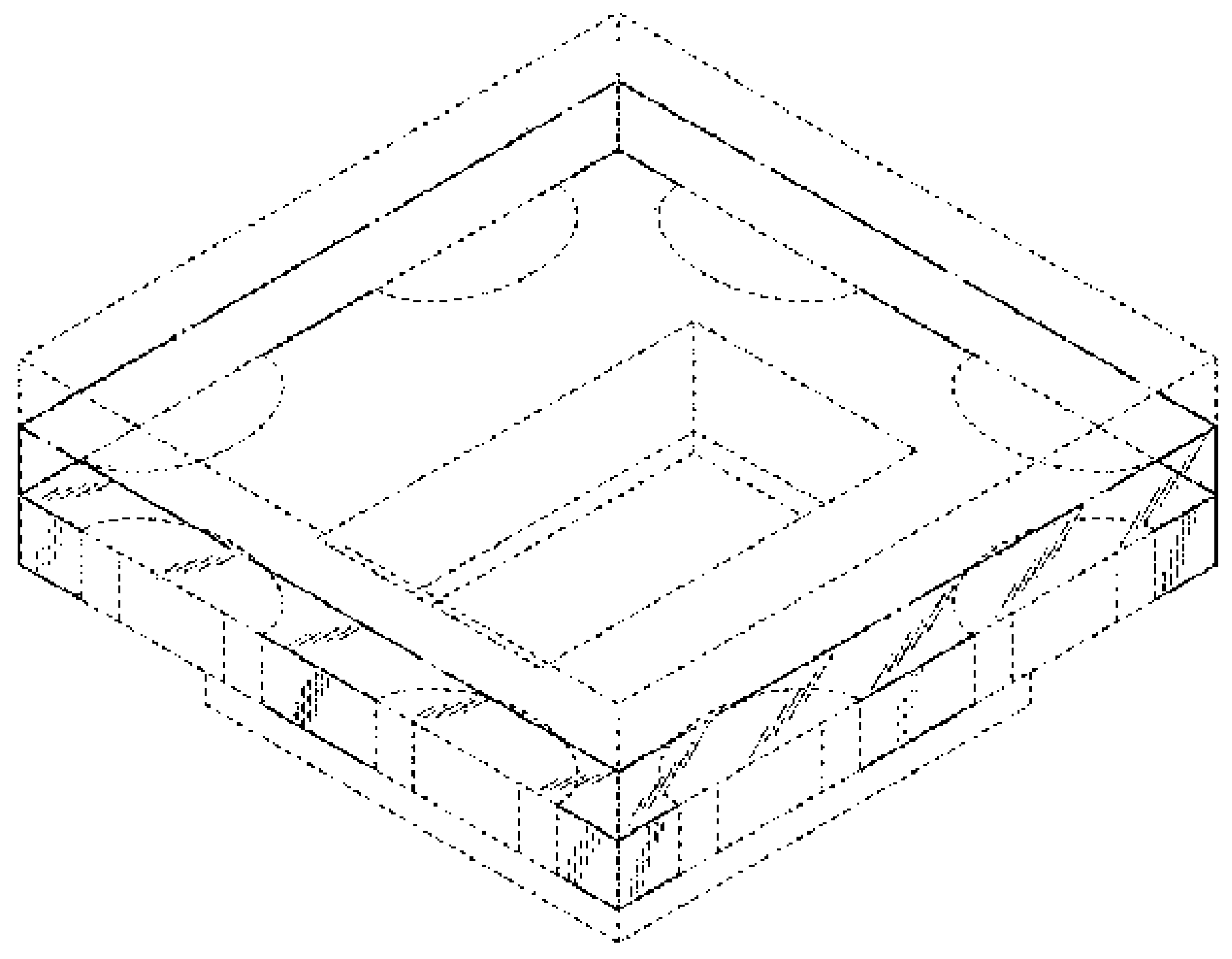

The evenly spaced broken lines are for the purpose of illustrating environment only and form no part of the claimed design.

1 Claim, 10 Drawing Sheets

Related U.S. Application Data

having an international filing date of Sep. 21, 2016, now Pat. No. Des. 831,593.

(58) **Field of Classification Search**
CPC ... H01L 33/62; H01L 33/486; H01L 27/1463; H01L 25/0753; H01L 33/44; C08G 77/04; B29C 45/0001; C08K 5/13; H01S 5/162; C08L 83/04
See application file for complete search history.

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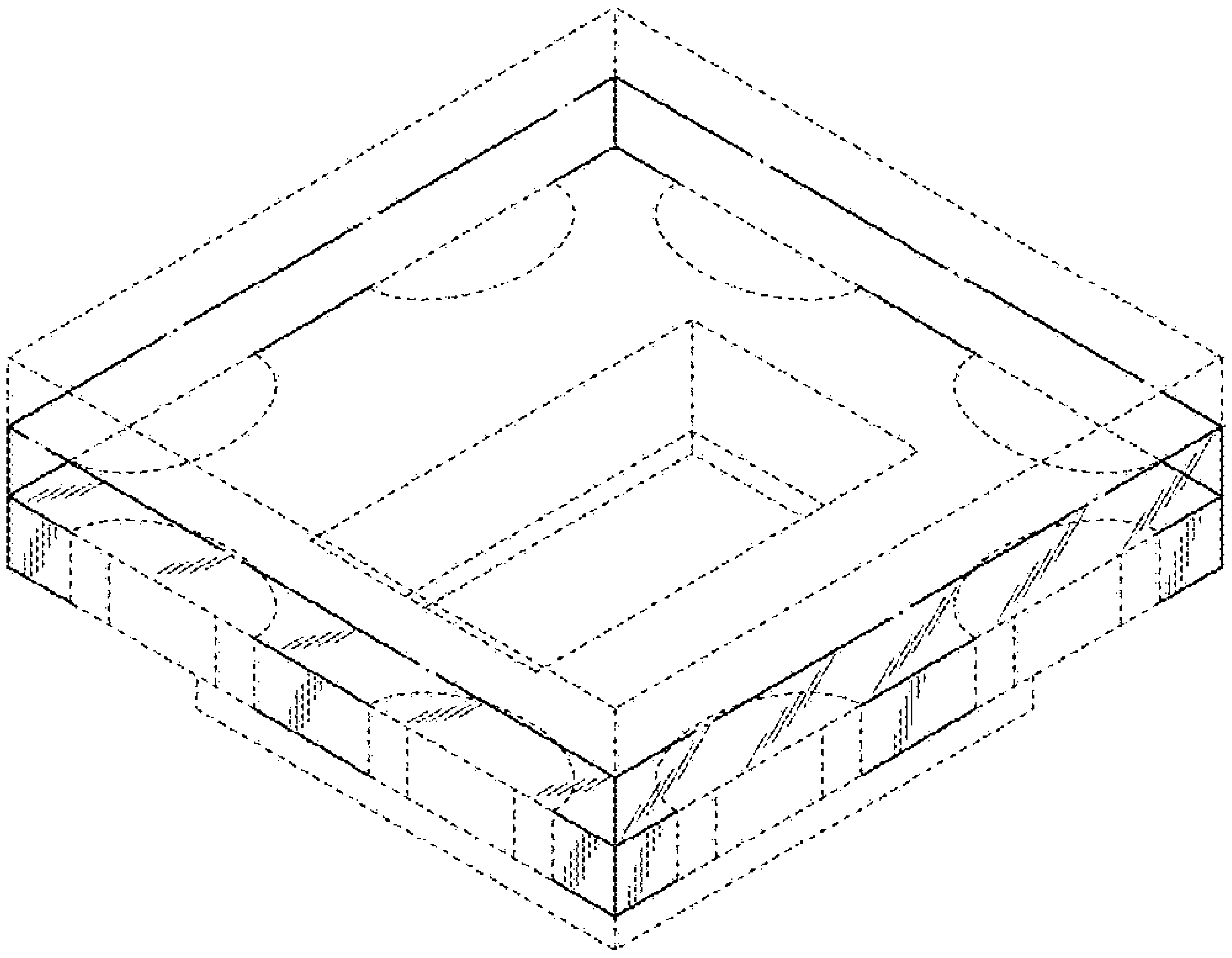


FIG. 1

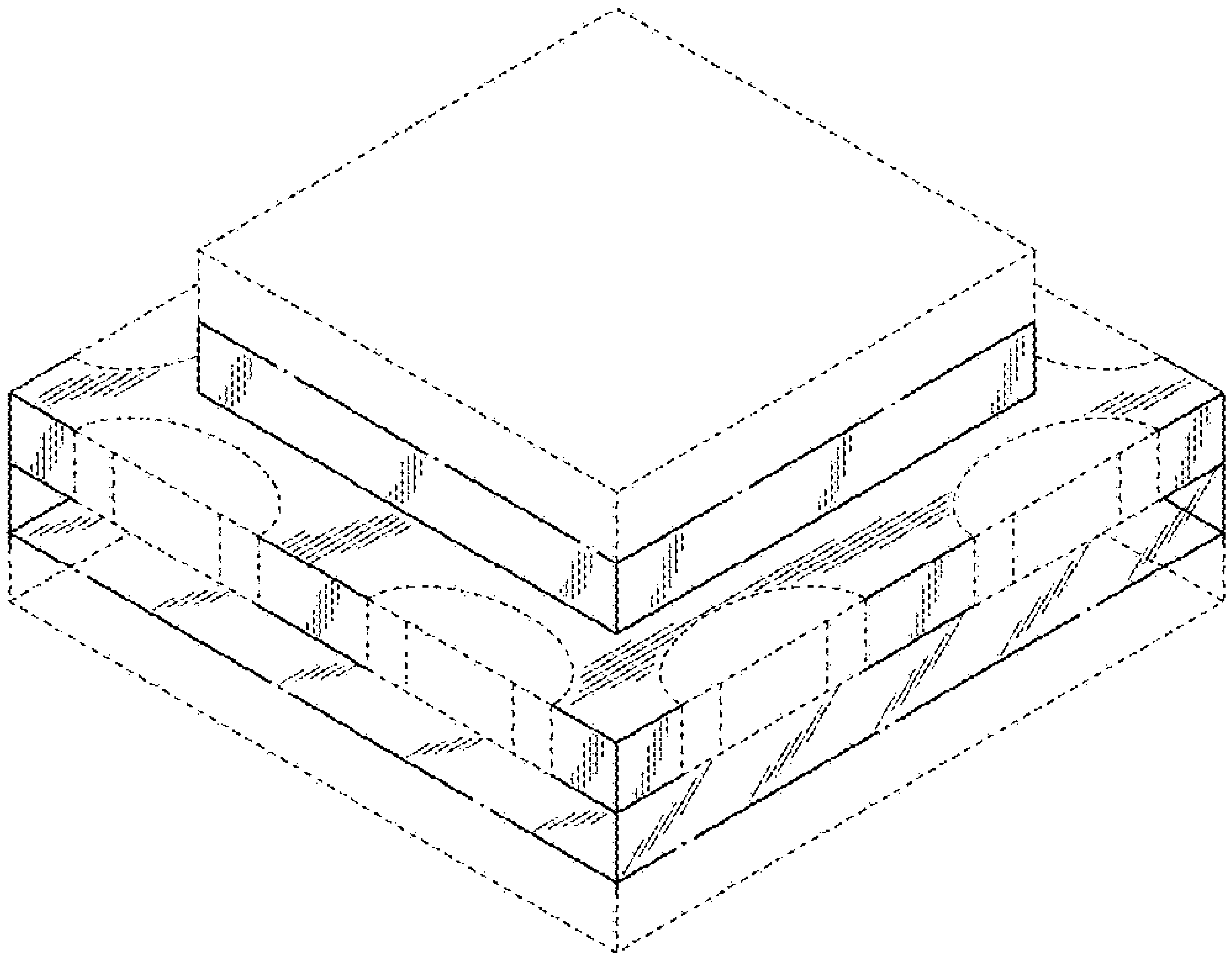


FIG. 2

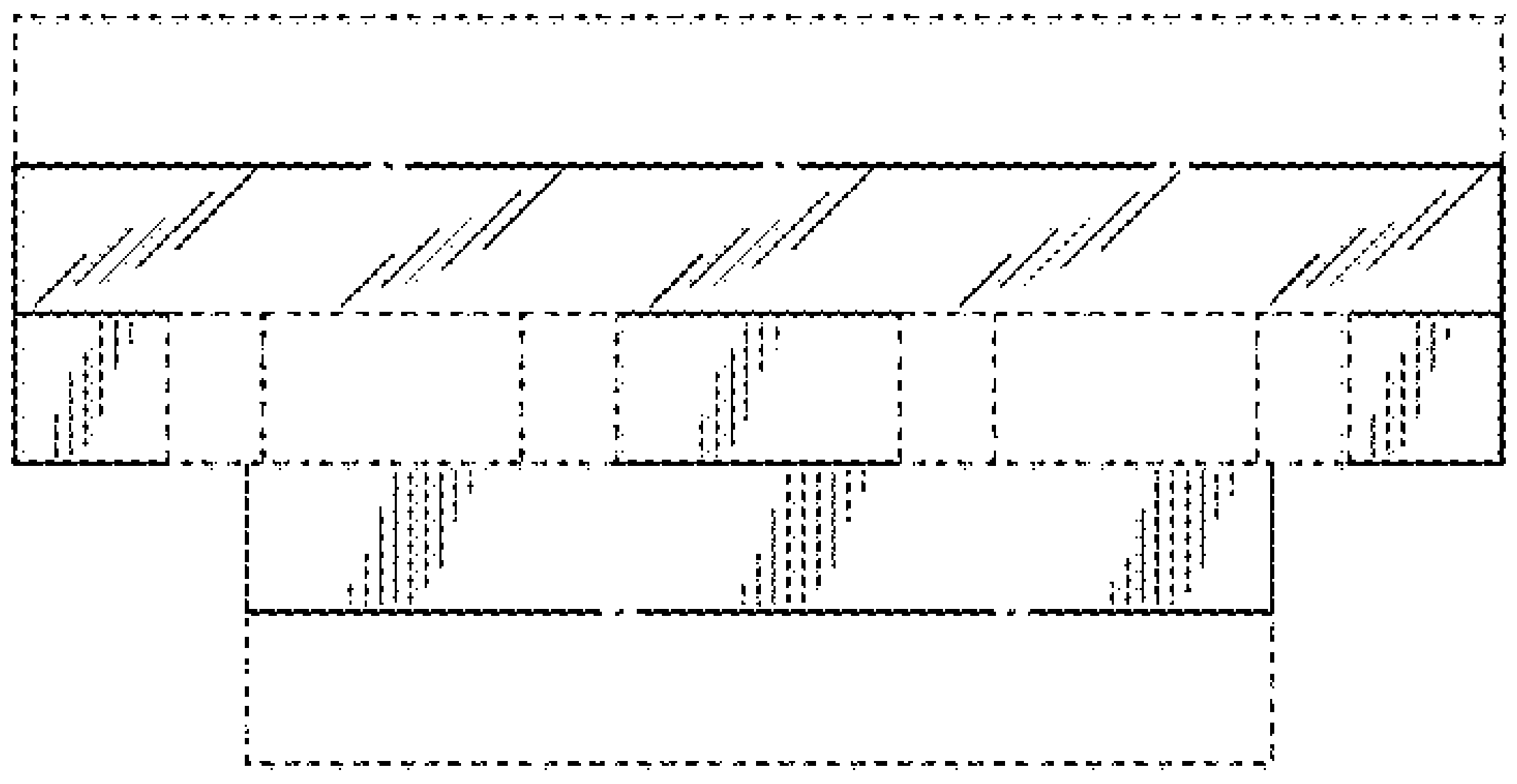
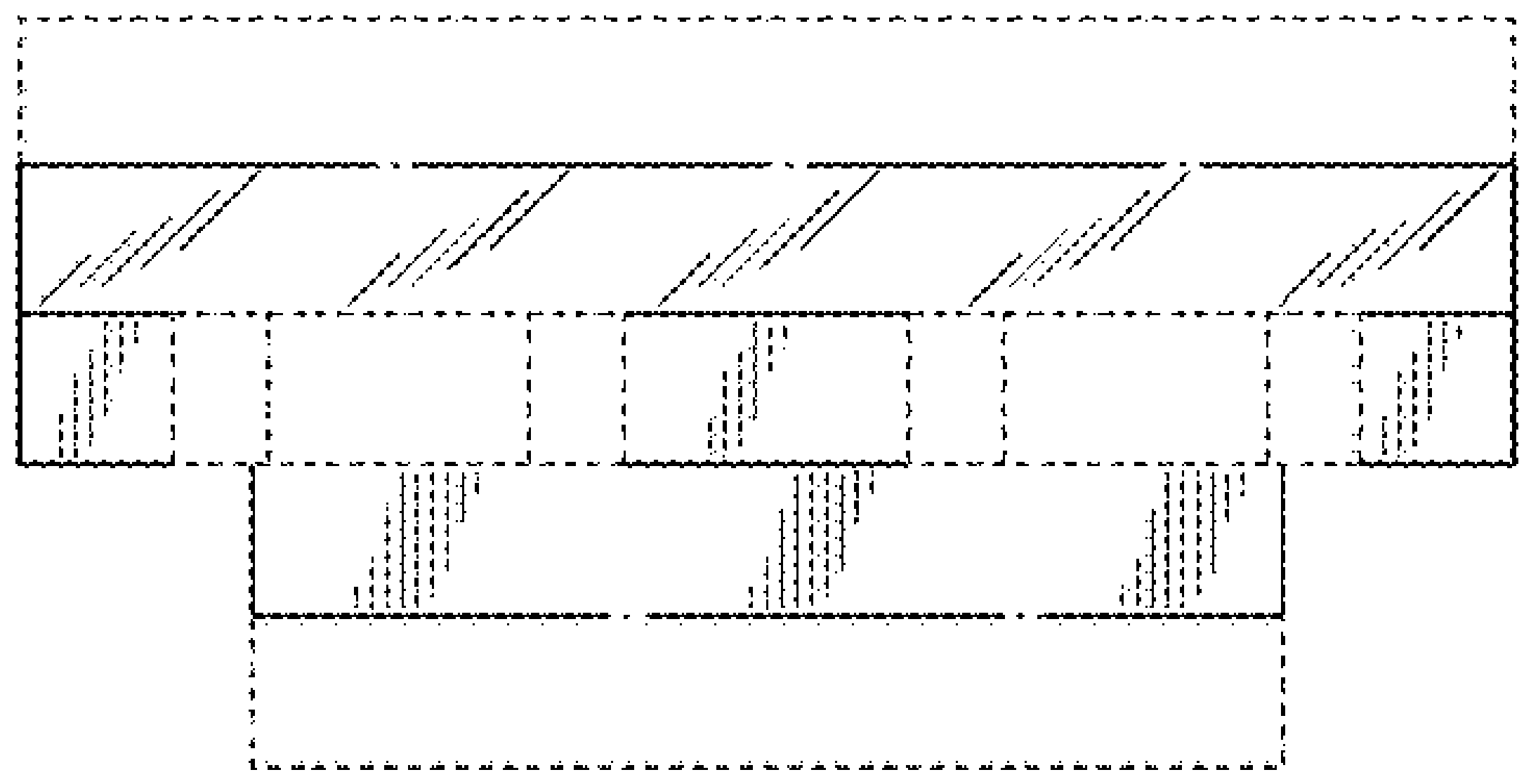


FIG. 3



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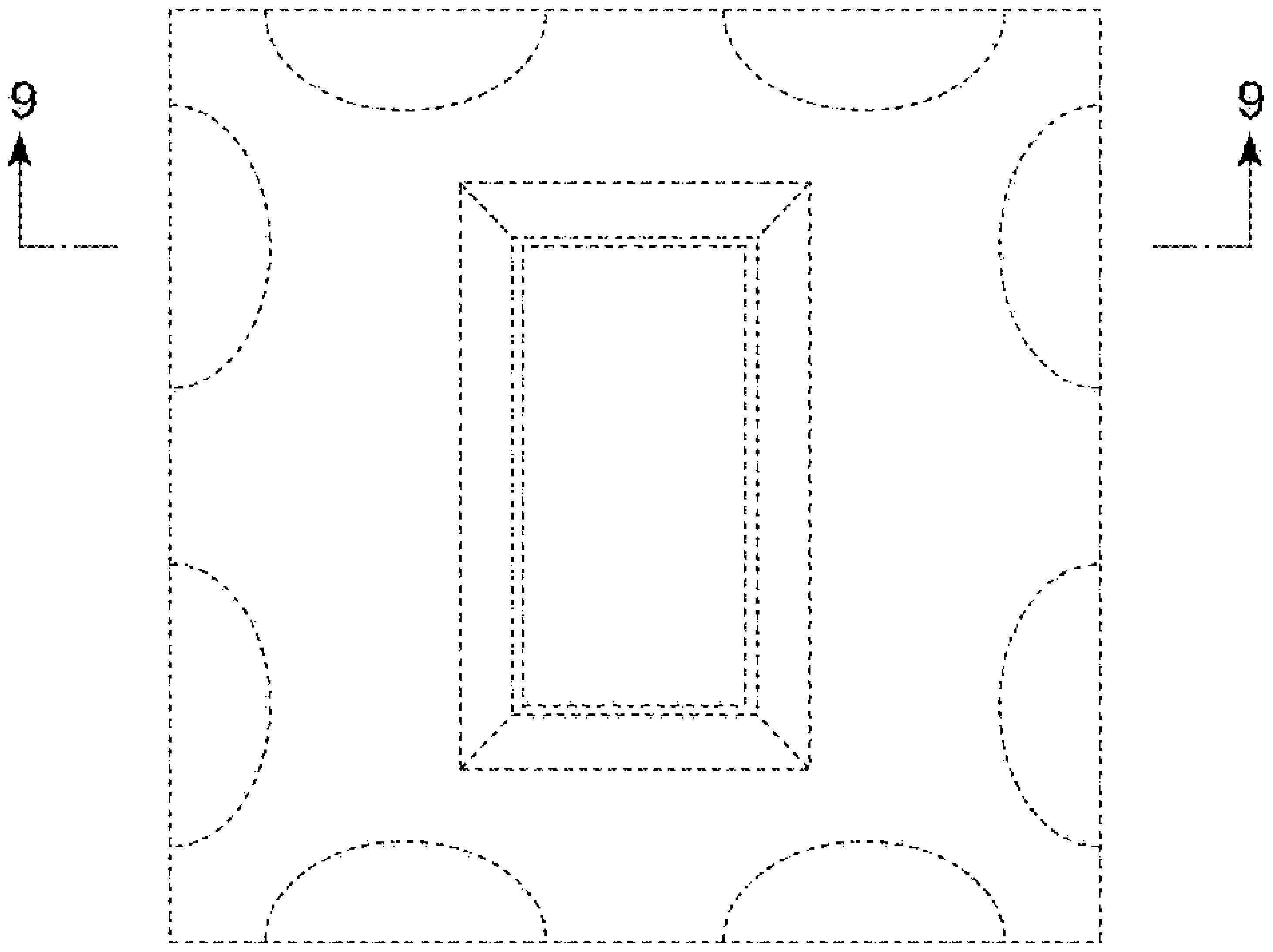

FIG. 5

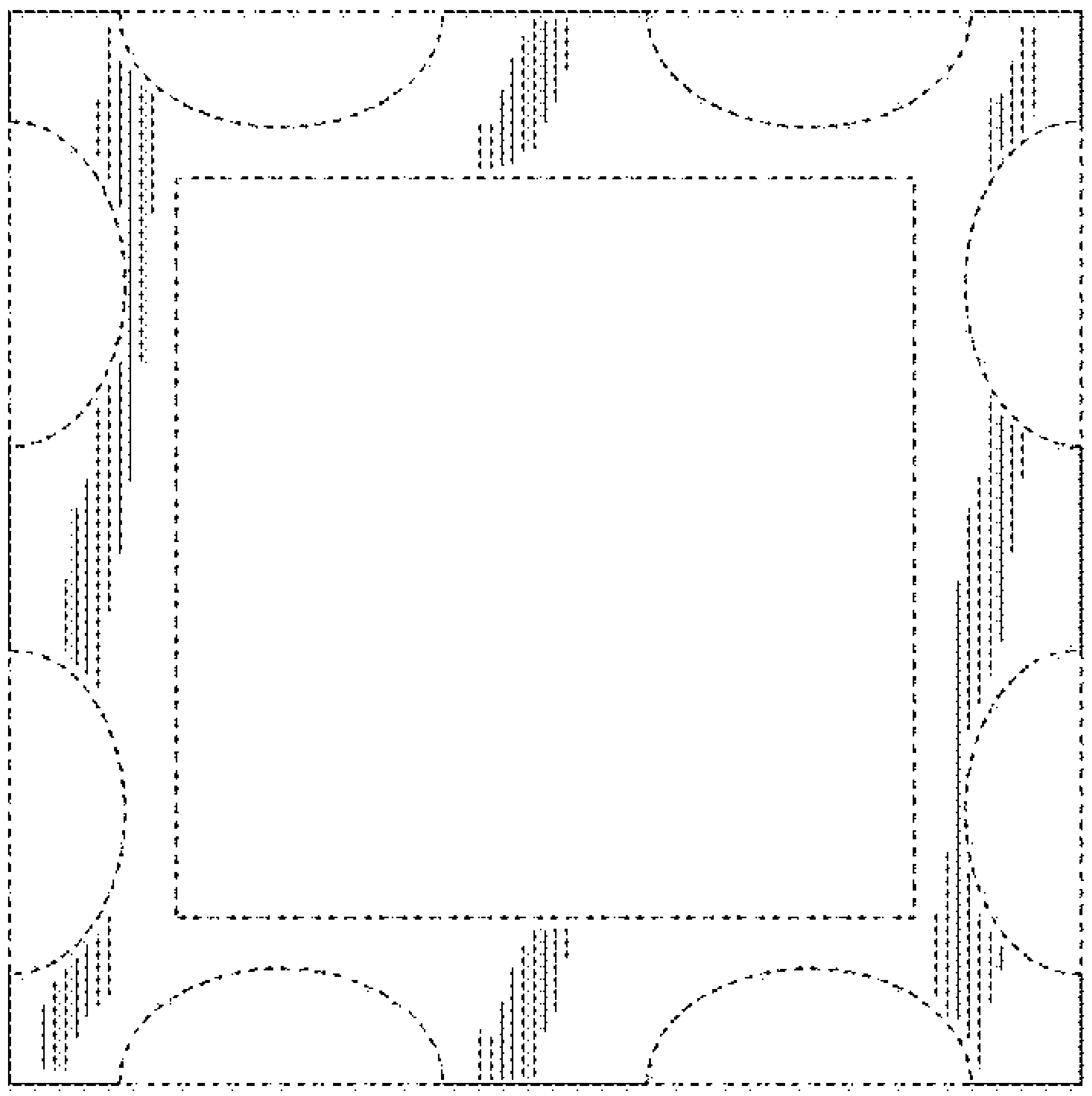

FIG. 6

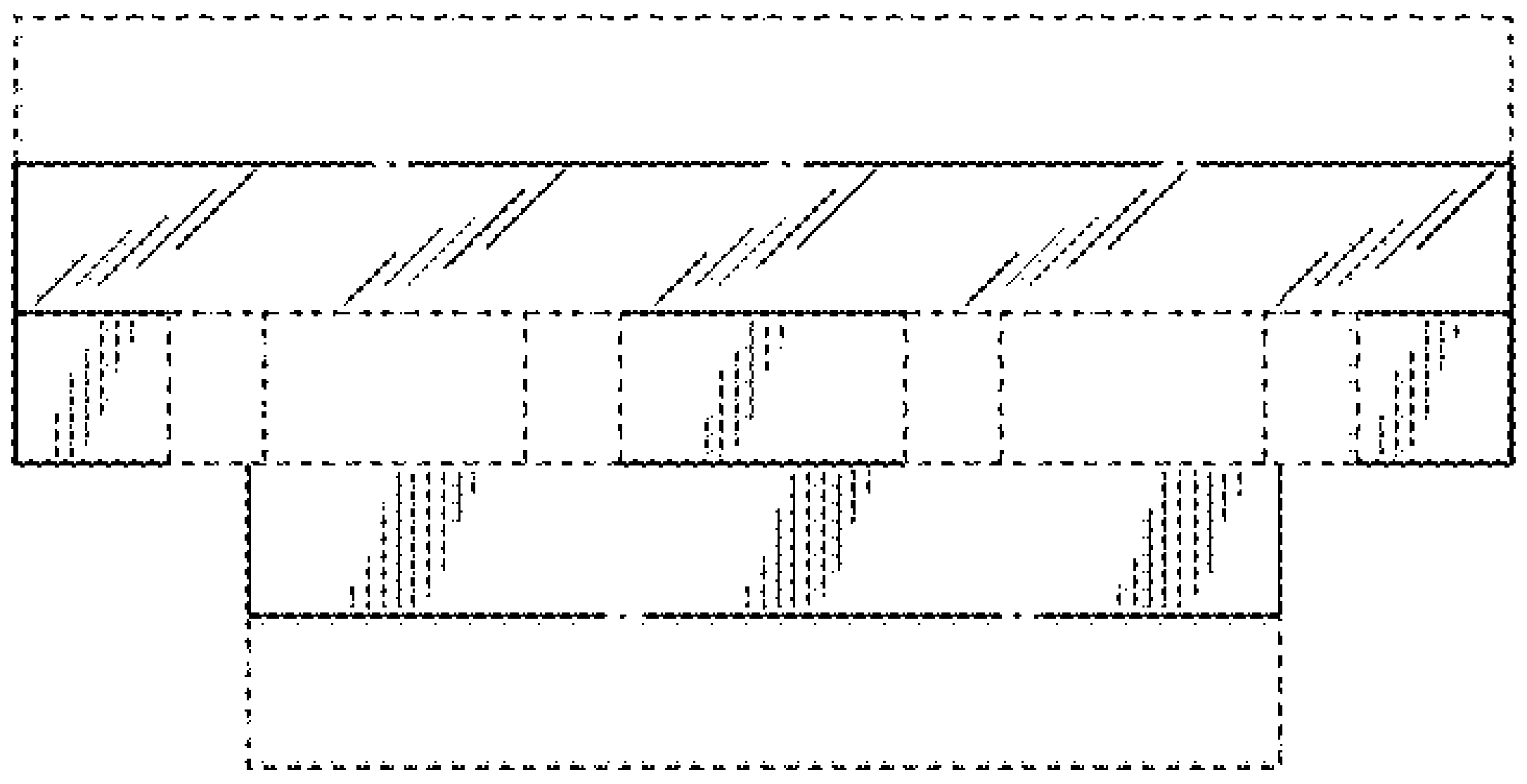

FIG. 7

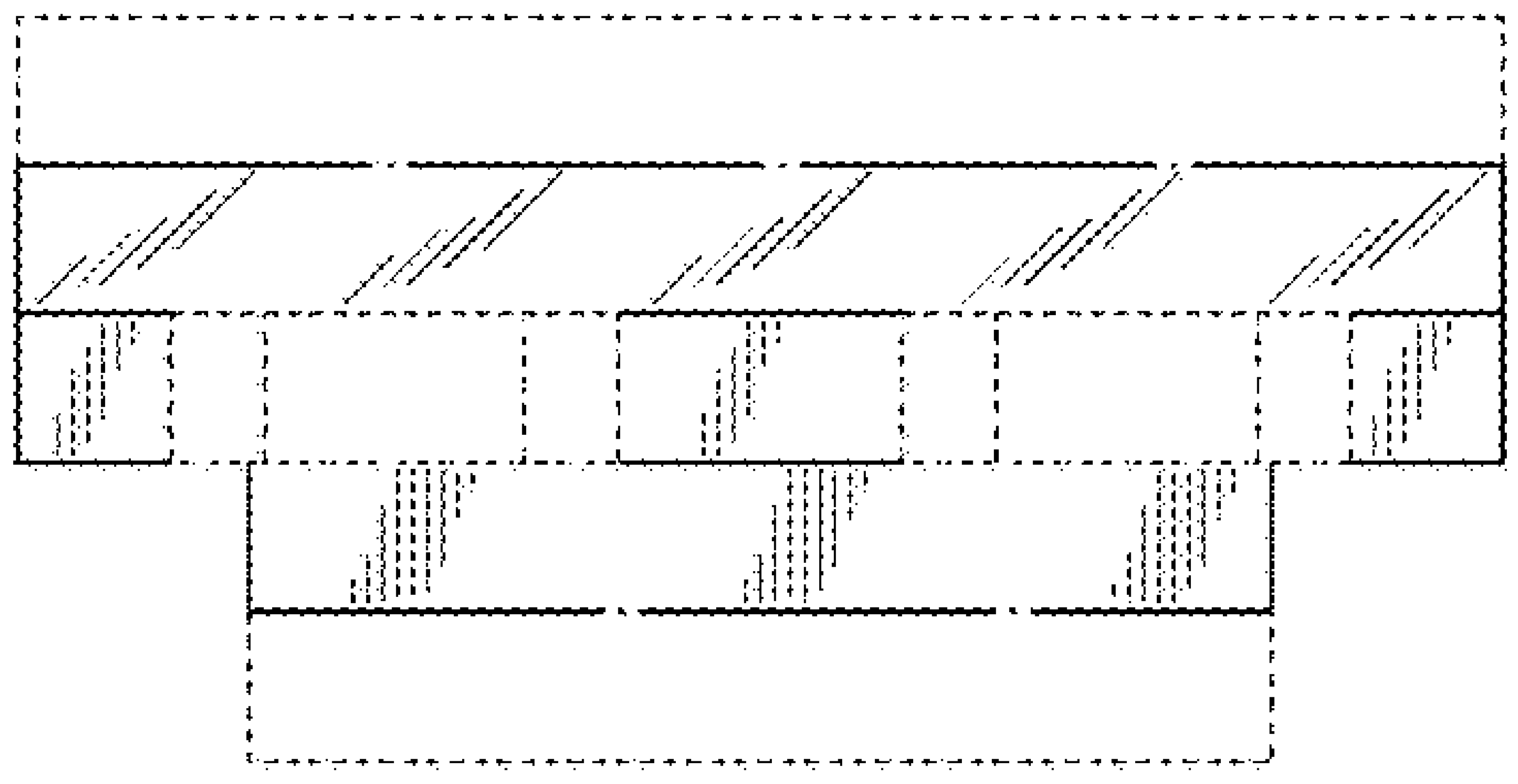

FIG. 8

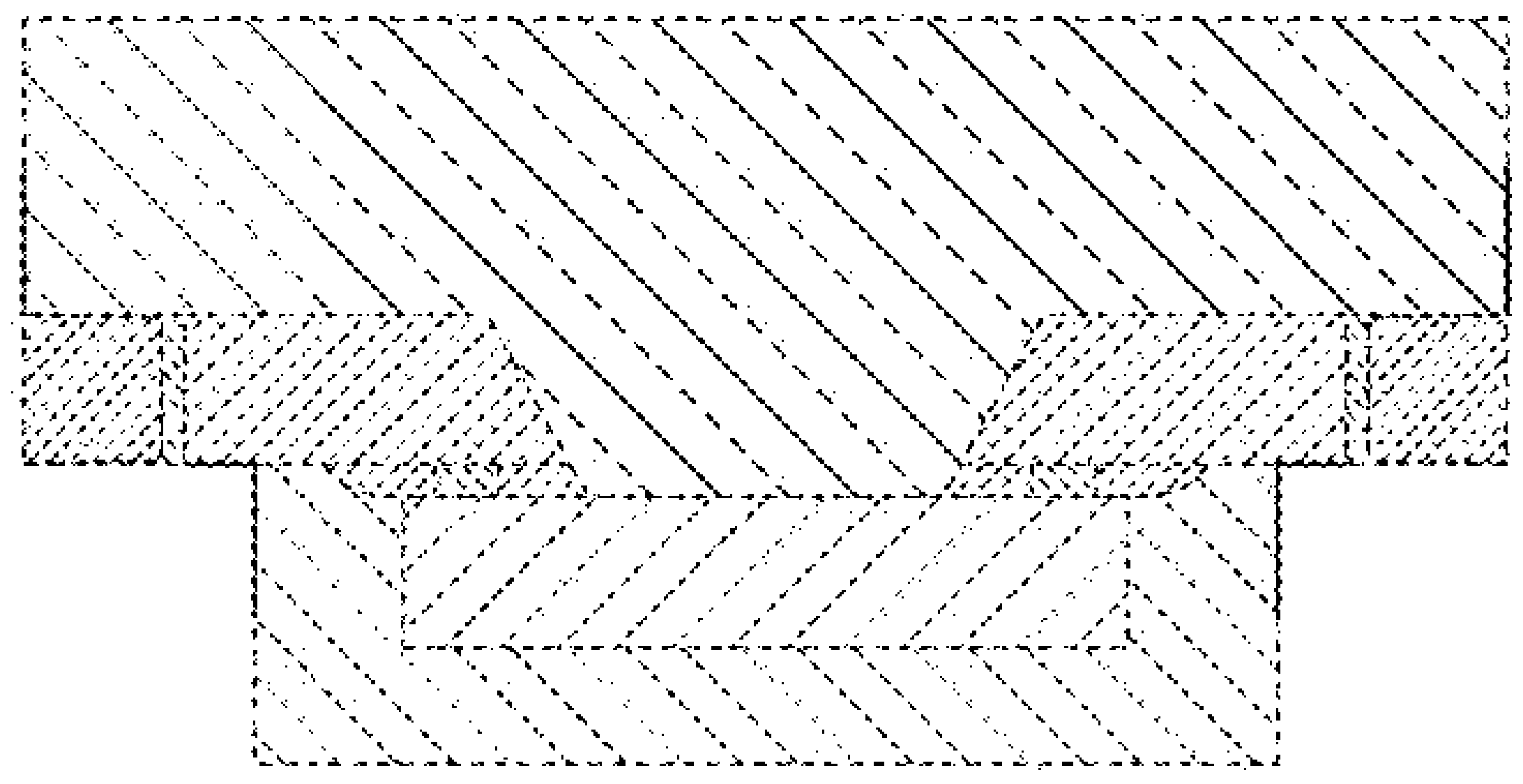

FIG. 9

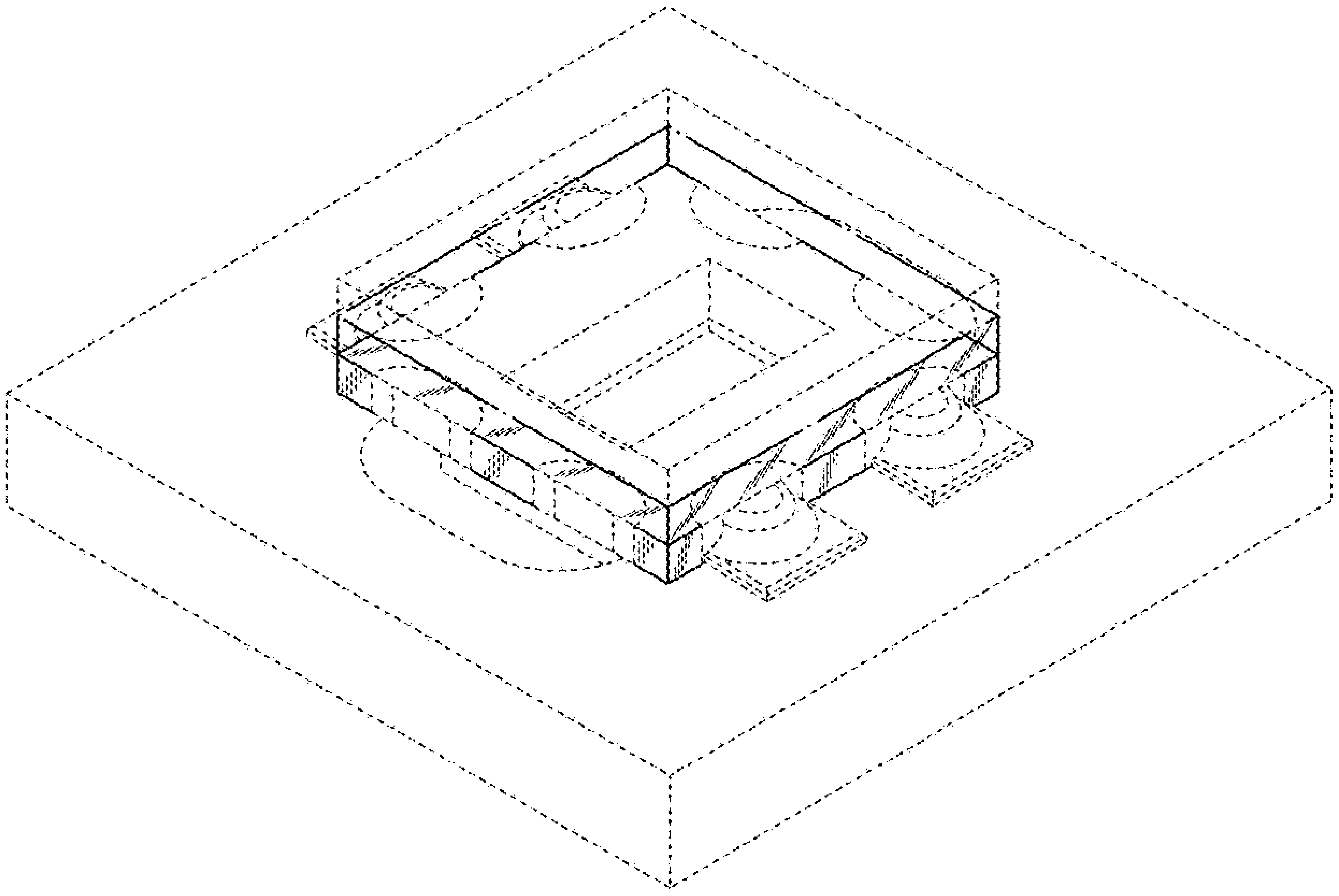

FIG. 10